

Title (en)

Method of fabricating a heat dissipator including coolant passage

Title (de)

Verfahren zur Herstellung einer Kühlungsdurchlass-enthaltenden Wärmesenke

Title (fr)

Méthode de fabrication d'un dissipateur de chaleur avec passage pour réfrigérant

Publication

EP 0902470 B1 20041006 (EN)

Application

EP 98305876 A 19980723

Priority

JP 23220097 A 19970828

Abstract (en)

[origin: EP0902470A2] A heat dissipator (10) includes a heat-conductive substrate (11), a lid (12) and a heat-conductive cover layer (13), and a coolant groove (15) for passing coolant is formed on a major surface of the substrate (11). The lid (12) is positioned on the coolant groove (15) to seal the same, and the cover layer (13) covers the major surface of substrate (11) and the lid (12). <IMAGE>

IPC 1-7

H01L 23/373; **H01L 23/46**

IPC 8 full level

H01L 23/373 (2006.01); **H01L 23/473** (2006.01); **H01S 5/00** (2006.01)

CPC (source: EP US)

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EP 0715314 A1 19960605 - SUMITOMO ELECTRIC INDUSTRIES [JP]

Cited by

EP1796165A3; FR2827079A1; GB2491685A; GB2491685B

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